

TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (U-MOSIV)

# TPCS8213

## Lithium Ion Battery Applications

- Small footprint due to a small and thin package
- Low drain-source ON-resistance:  $R_{DS(ON)} = 8.4 \text{ m}\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 13 \text{ S}$  (typ.)
- Low leakage current:  $I_{DSS} = 10 \text{ }\mu\text{A}$  (max) ( $V_{DS} = 20 \text{ V}$ )
- Enhancement-mode:  $V_{th} = 0.5\sim 1.4 \text{ V}$  ( $V_{DS} = 10 \text{ V}$ ,  $I_D = 200 \text{ }\mu\text{A}$ )
- Common drain

## Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit
Drain-source voltage		$V_{DSS}$	20	V
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )		$V_{DGR}$	20	V
Gate-source voltage		$V_{GSS}$	$\pm 12$	V
Drain current	DC (Note 1)	$I_D$	6	A
	Pulse (Note 1)	$I_{DP}$	24	
Drain power dissipation ( $t = 10 \text{ s}$ ) (Note 2a)	Single-device operation (Note 3a)	$P_D$ (1)	1.1	W
	Single-device value at dual operation (Note 3b)	$P_D$ (2)	0.75	
Drain power dissipation ( $t = 10 \text{ s}$ ) (Note 2b)	Single-device operation (Note 3a)	$P_D$ (1)	0.6	W
	Single-device value at dual operation (Note 3b)	$P_D$ (2)	0.35	
Single-pulse avalanche energy (Note 4)		$E_{AS}$	9.4	mJ
Avalanche current		$I_{AR}$	6	A
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		$E_{AR}$	0.075	mJ
Channel temperature		$T_{ch}$	150	°C
Storage temperature range		$T_{stg}$	-55~150	°C

Note: For Notes 1 to 5, see the next page.

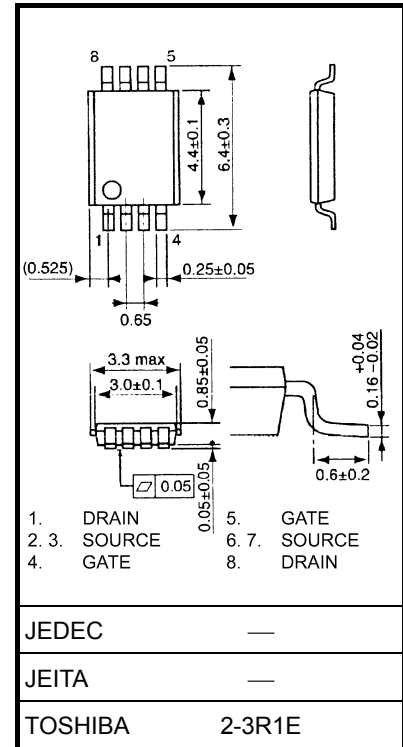
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

This transistor is an electrostatic-sensitive device. Handle with care.

### WARNING

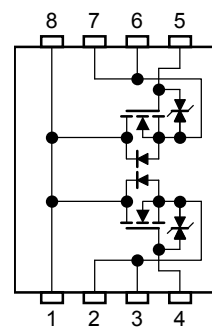
**【Handling Precaution for Power MOSFET in use of Protection Circuit for Battery Pack】**  
 Flame-retardant resins of UL94-V0 flammability class are used in packages, however, they are not noncombustible. Use a unit, for example PTC Thermistor, which can shut off the power supply if a short-circuit occurs. If the power supply is not shut off on the occurring short-circuit, a large short-circuit current will flow continuously, which may cause the device to catch fire or smoke.

Unit: mm



Weight: 0.035 g (typ.)

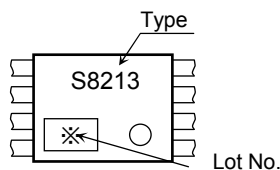
## Circuit Configuration



## Thermal Characteristics

Characteristic		Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s)	Single-device operation (Note 3a)	R <sub>th (ch-a)</sub> (1)	114	°C/W
	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a)</sub> (2)	167	
Thermal resistance, channel to ambient (t = 10 s)	Single-device operation (Note 3a)	R <sub>th (ch-a)</sub> (1)	208	°C/W
	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a)</sub> (2)	357	

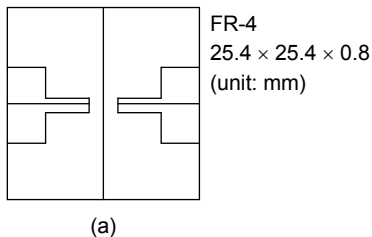
## Marking (Note 6)



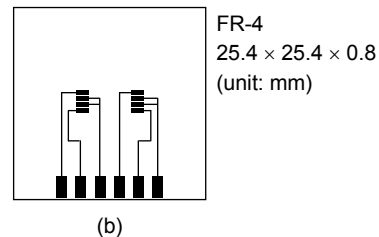
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:

a) Device mounted on a glass-epoxy board (a)



b) Device mounted on a glass-epoxy board (b)



Note 3:

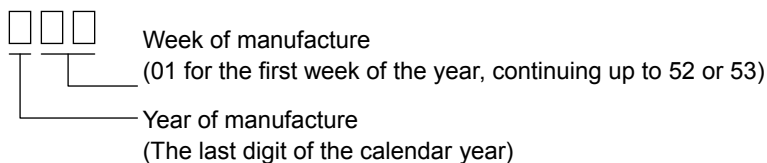
- a) The power dissipation and thermal resistance values are shown for a single device. (During single-device operation, power is applied to one device only.)
- b) The power dissipation and thermal resistance values are shown for a single device. (During dual operation, power is applied to both devices evenly.)

Note 4: V<sub>DD</sub> = 16 V, T<sub>ch</sub> = 25°C (initial), L = 0.2 mH, R<sub>G</sub> = 25 Ω, I<sub>AR</sub> = 6 A

Note 5: Repetitive rating: pulse width limited by max channel temperature

Note 6: The circle "o" on lower right of the marking indicates Pin 1.

\* Weekly code (three digits):

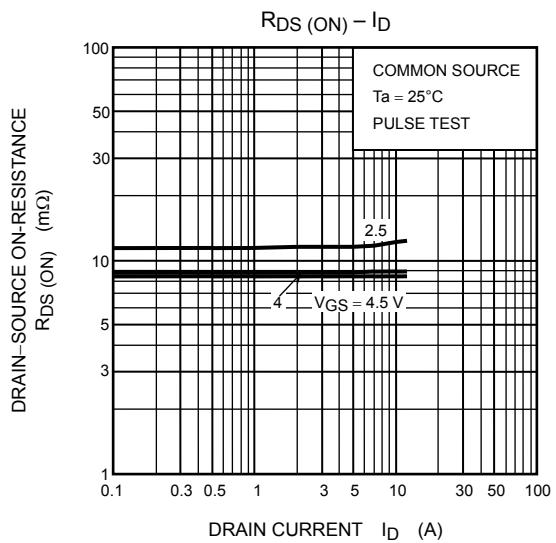
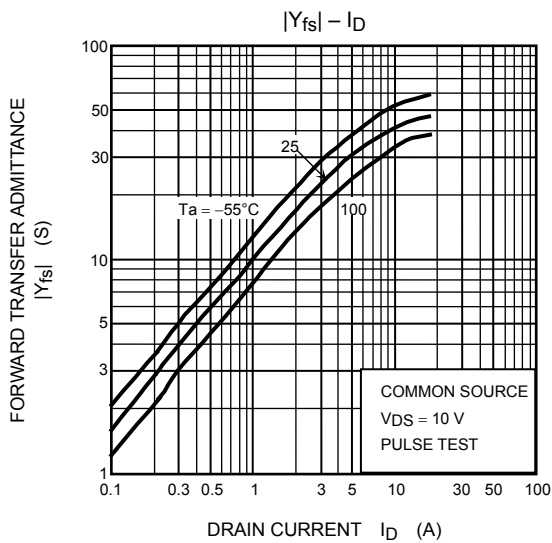
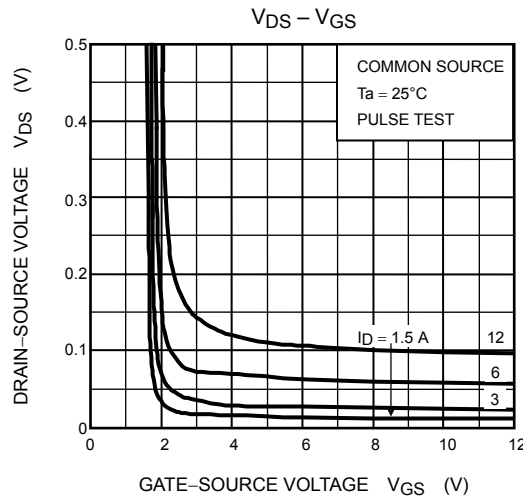
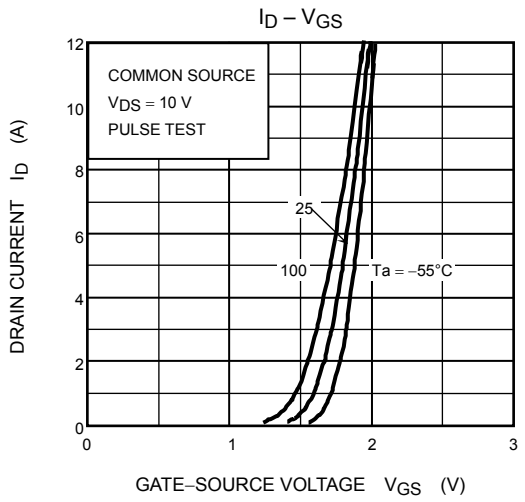
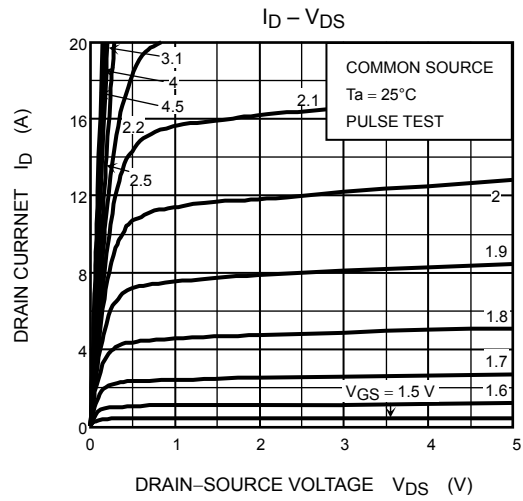
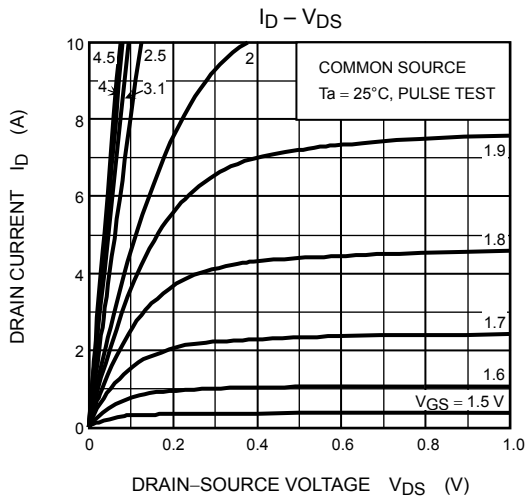


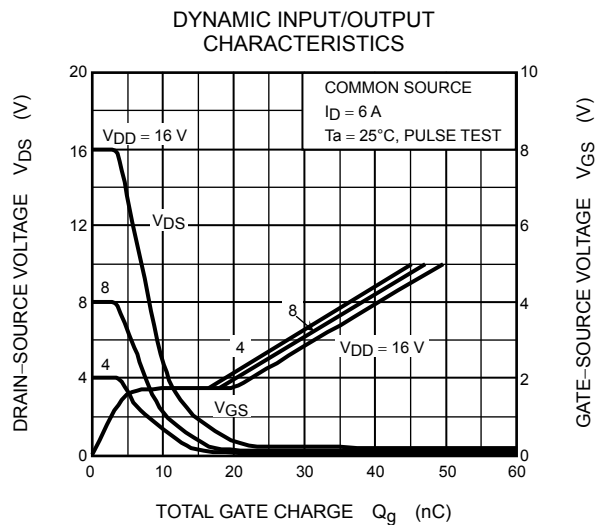
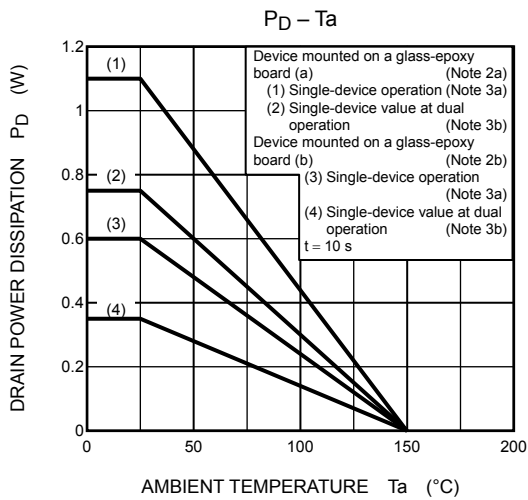
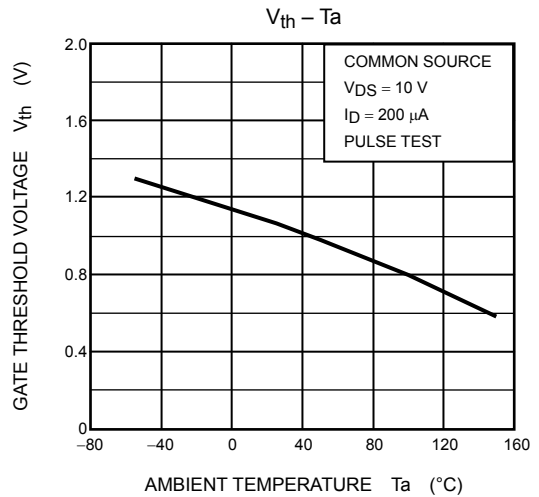
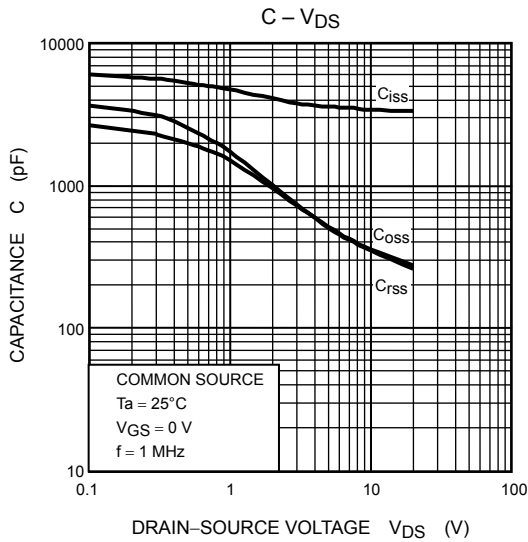
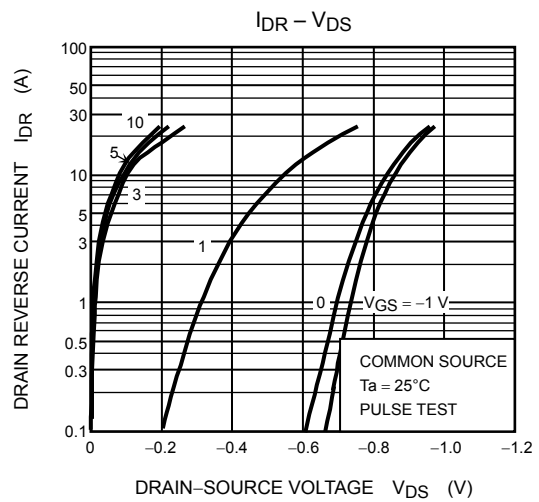
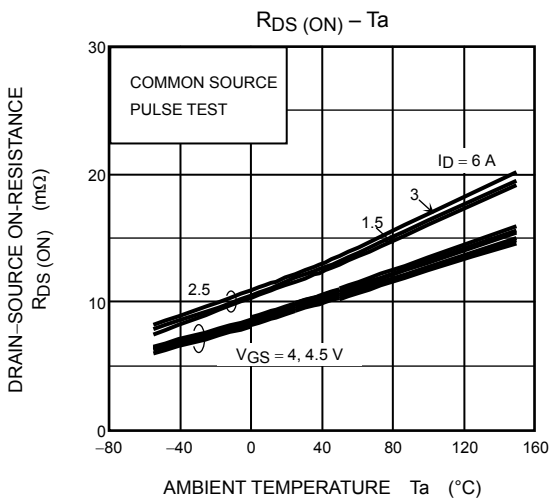
## Electrical Characteristics (Ta = 25°C)

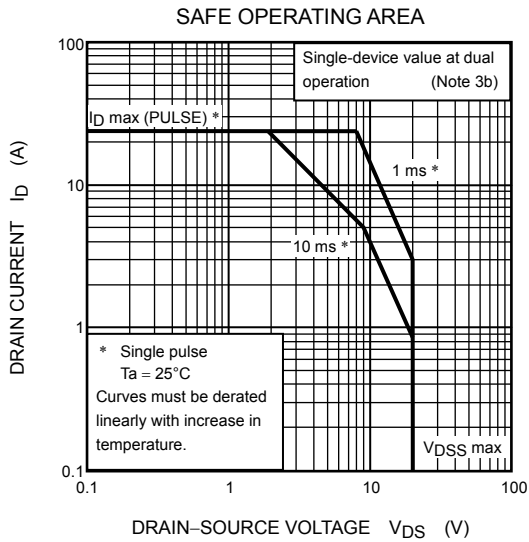
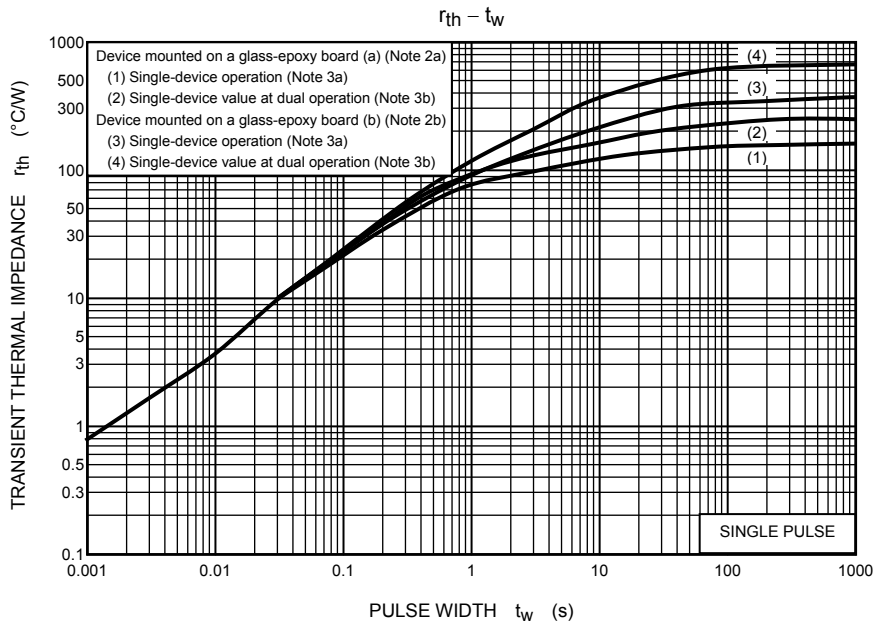
Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		$I_{GSS}$	$V_{GS} = \pm 10\text{ V}, V_{DS} = 0\text{ V}$	—	—	$\pm 10$	$\mu\text{A}$
Drain cutoff current		$I_{DSS}$	$V_{DS} = 20\text{ V}, V_{GS} = 0\text{ V}$	—	—	10	$\mu\text{A}$
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$	20	—	—	V
		$V_{(BR)DSX}$	$I_D = 10\text{ mA}, V_{GS} = -12\text{ V}$	8	—	—	
Gate threshold voltage		$V_{th}$	$V_{DS} = 10\text{ V}, I_D = 200\text{ }\mu\text{A}$	0.5	—	1.4	V
Drain-source ON-resistance		$R_{DS(ON)}$	$V_{GS} = 2.5\text{ V}, I_D = 4.2\text{ A}$	—	11	18	m $\Omega$
			$V_{GS} = 4.0\text{ V}, I_D = 4.8\text{ A}$	—	8.7	13	
			$V_{GS} = 4.5\text{ V}, I_D = 4.8\text{ A}$	—	8.4	12	
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = 10\text{ V}, I_D = 3.0\text{ A}$	6.5	13	—	S
Input capacitance		$C_{iss}$	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	3140	—	pF
Reverse transfer capacitance		$C_{rss}$		—	385	—	
Output capacitance		$C_{oss}$		—	425	—	
Switching time	Rise time	$t_r$	<p> <math>V_{GS} = 5\text{ V}</math>  <math>0\text{ V}</math>  <math>I_D = 3\text{ A}</math>  <math>V_{OUT}</math>  <math>4.7\text{ }\Omega</math>  <math>V_{DD} \approx 10\text{ V}</math>  <math>R_L = 3.3\text{ }\Omega</math>                      Duty <math>\leq 1\%</math>, <math>t_w = 10\text{ }\mu\text{s}</math> </p>	—	20	—	ns
	Turn-on time	$t_{on}$		—	30	—	
	Fall time	$t_f$		—	23	—	
	Turn-off time	$t_{off}$		—	84	—	
Total gate charge (gate-source plus gate-drain)		$Q_g$	$V_{DD} \approx 16\text{ V}, V_{GS} = 5\text{ V}, I_D = 6\text{ A}$	—	49	—	nC
Gate-source charge 1		$Q_{gs1}$		—	6	—	
Gate-drain ("Miller") charge		$Q_{gd}$		—	13	—	

## Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Drain reverse current	Pulse (Note 1)	$I_{DRP}$	—	—	—	24	A
Forward voltage (diode)		$V_{DSF}$	$I_{DR} = 6\text{ A}, V_{GS} = 0\text{ V}$	—	—	-1.2	V







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